AMENDMENTS TO THE CLAIMS

Claims 1-4 (Canceled)

Claim 5 (Previously Presented): A wave plate comprising at least two retardation films, which are obtained by stretch-orientating cycloolefin resin films and which are laminated on each other,

wherein on at least one surface of said laminated retardation films a glass substrate is laminated, and

wherein the retardation films, and the retardation film and the glass substrate are lamination-fixed respectively with different adhesives which are selected from the following adhesives (A) and (B):

an adhesive (A) having a glass transition temperature of not higher than 0°C and a Young's modulus at 23°C of not more than 10 MPa, and

an adhesive (B) having a glass transition temperature of not lower than 40°C and a Young's modulus at 23°C of not less than 30 MPa,

with the proviso that a difference in glass transition temperature between the adhesive (A) and the adhesive (B) is 60°C or more and a difference in Young's modulus at 23°C between the adhesive (A) and the adhesive (B) is 40 MPa or more.

Claim 6 (Original): The wave plate as claimed in claim 5, wherein on both surfaces of the laminated retardation films glass substrates are laminated, the retardation films are lamination-fixed to each other with the adhesive (A), and the retardation film and the glass substrate are fixed to each other with the adhesive (B).

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Claim 7 (Canceled)

Claim 8 (Previously Presented): A process for producing a wave plate, the process comprising

laminating at least two retardation films on each other, where the retardation films are obtained by stretch-orientating cycloolefin resin films; and

laminating a glass substrate on at least one surface of the laminated retardation films, wherein

the retardation films, and the retardation film and the glass substrate are lamination-fixed respectively with different adhesives which are selected from the following adhesives (A) and (B):

an adhesive (A) having a glass transition temperature of not higher than 0°C and a Young's modulus at 23°C of not more than 10 MPa, and

an adhesive (B) having a glass transition temperature of not lower than 40°C and a Young's modulus at 23°C of not less than 30 MPa,

with the proviso that a difference in glass transition temperature between the adhesive (A) and the adhesive (B) is 60°C or more and a difference in Young's modulus at 23°C between the adhesive (A) and the adhesive (B) is 40 MPa or more.

Claim 9 (New): The wave plate as claimed in claim 5, wherein the cycloolefin resin films comprise cycloolefin resin having a glass transition temperature in a range of from 120 to 350°C.

Claim 10 (New): The wave plate as claimed in claim 5, wherein each of the cycloolefin resin films has a linear expansion coefficient in a temperature range of 20 to 100° C of not more than 1×10^{-4} (1/°C).

Claim 11 (New): The wave plate as claimed in claim 5, wherein the glass substrate has a thickness in a range of from 0.01 to 5 mm.

Claim 12 (New): The wave plate as claimed in claim 5, wherein the adhesive (A) is selected from the group consisting of natural rubber adhesives, synthetic rubber adhesives, vinyl acetate/vinyl chloride copolymer adhesives, silicon adhesives, polyvinyl ether adhesives, acrylic adhesives, epoxy adhesives and urethane adhesives.

Claim 13 (New): The wave plate as claimed in claim 5, wherein the adhesive (A) is an acrylic adhesive.

Claim 14 (New): The wave plate as claimed in claim 5, wherein the adhesive (B) is selected from the group consisting of natural rubber adhesives, synthetic rubber adhesives, vinyl acetate/vinyl chloride copolymer adhesives, silicon adhesives, polyvinyl ether adhesives, acrylic adhesives, epoxy adhesives and urethane adhesives.

Claim 15 (New): The wave plate as claimed in claim 5, wherein the adhesive (B) is an acrylic adhesive.